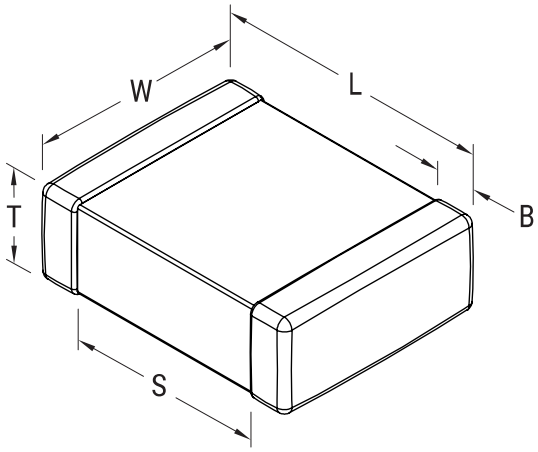
C1206C103J5GECTU

Aliases (C1206C103J5GEC7800)

ESD SMD Comm C0G, Ceramic, 0.01 uF, 5%, 50 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



Click here for the 3D model.

General Information	
Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	0.9mm +/-0.10mm
S	1.5mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	5%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms